

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Canceled)

2. (Currently Amended) ~~The electrical component of claim 1,~~ An electrical

component comprising:

a substrate;

a first electrode layer;

a growth layer that is structured and that is thinner than the first electrode layer;

a piezoelectric layer; and

a second electrode layer,

wherein the growth layer is on the first electrode layer, the growth layer is structured relative to the first electrode layer, and the growth layer has a smaller surface area than the first electrode layer.

3. (Currently Amended) ~~The electrical component of claim 1,~~ An electrical

component comprising:

a substrate;

a first electrode layer;

a growth layer that is structured and that is thinner than the first electrode layer;

a piezoelectric layer; and

a second electrode layer,

wherein the piezoelectric layer (i) substantially covers the growth layer and (ii) overlaps the growth layer along a perimeter of the growth layer, thereby causing the piezoelectric layer and the first electrode layer to substantially enclose the growth layer.

4. (Currently Amended) The electrical component of claim [[1]] 8, wherein the growth layer supports ordered growth relative to the piezoelectric layer.

5. (Currently Amended) The electrical component of claim [[1]] 8, wherein the growth layer comprises at least one of the following: Au, Mo, W, Pt, Si₃N₄, sapphire, spinel, Si, Ba₃TiO₃, ZrO₂, MgO, and TiO₂.

6. (Currently Amended) The electrical component of claim [[1]] 8, wherein the piezoelectric layer comprises at least one of AlN and ZnO.

7. (Currently Amended) The electrical component of claim [[1]] 2, wherein the first electrode layer comprises multiple layers, the multiple layers comprising a titanium layer and another layer that is not titanium.

8. (Currently Amended) ~~The electrical component of claim 1, further comprising:~~ An electrical component comprising:

a substrate;

a first electrode layer;

a growth layer that is structured and that is thinner than the first electrode layer;

a piezoelectric layer;

a second electrode layer; and

an acoustic mirror between the substrate and the first electrode layer.

9. (Currently Amended) ~~The electrical component of claim 1, further comprising:~~ An electrical component comprising:

a substrate;

a first electrode layer;

a growth layer that is structured and that is thinner than the first electrode layer;

a piezoelectric layer;

a second electrode layer;

a multilayer structure comprising a plurality of piezoelectric layers; and

an additional electrode layer and an additional growth layer between pairs of the plurality of piezoelectric layers.

10. (Currently Amended) A piezoelectric actuator comprising the electrical component of claim [[1]]9.

11. (Currently Amended) A bulk acoustic wave resonator comprising:
the electrical component of claim [[1]]8.

12. (Withdrawn) A method of producing a component that includes at least one bulk acoustic wave resonator, the method comprising:

applying a first electrode layer to a substrate;

structuring the first electrode layer to produce a first electrode region;

applying a growth layer to the first electrode region;

structuring the growth layer ~~such~~ to produce a growth region over the first electrode region, the growth region having a smaller surface area than the first electrode region;

growing a piezoelectric layer having crystal-axis oriented growth over the growth region;

structuring the piezoelectric layer so that the piezoelectric layer completely covers the growth region and so that the piezoelectric layer overlaps the growth region along a perimeter of the growth region wherein the first electrode layer and the piezoelectric layer enclose the growth region;

applying a second electrode layer above the piezoelectric layer relative to the first electrode layer; and

structuring the second electrode layer.

13. (Withdrawn) The method of claim 12, wherein structuring the growth layer is performed via wet chemical etching.

14. (Withdrawn) The method of claim 12, wherein applying the growth layer comprises vapor-depositing a gold layer.

15. (Withdrawn) The method of claim 12, wherein growing the piezoelectric layer is performed via a CVD or PVD process.

16. (Previously Presented) The electrical component of claim 2, wherein the piezoelectric layer (i) substantially covers the growth layer and (ii) overlaps the growth layer along a perimeter of the growth layer, thereby causing the piezoelectric layer and the first electrode layer to substantially enclose the growth layer.

17. (Previously Presented) The electrical component of claim 2, wherein the growth layer supports ordered growth relative to the piezoelectric layer.

18. (Previously Presented) The electrical component of claim 2, wherein the growth layer comprises at least one of the following: Au, Mo, W, Pt, Si₃N₄, sapphire, spinel, Si,

Ba₃TiO₃, ZrO₂, MgO, and TiO₂.

19. (Previously presented) The electrical component of claim 2, wherein the piezoelectric layer comprises at least one of AlN and ZnO.

20. (Previously Presented) The electrical component of claim 2, wherein the first electrode layer comprises multiple layers, the multiple layers comprising a titanium layer and another layer that is not titanium.

21. (New) The electrical component of claim 8, wherein the first electrode layer comprises multiple layers, the multiple layers comprising a titanium layer and another layer that is not titanium.